LNJ818C8DRA

Surface Mounting Chip LED

Dome-Lens Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	60	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	100	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Lighting Color

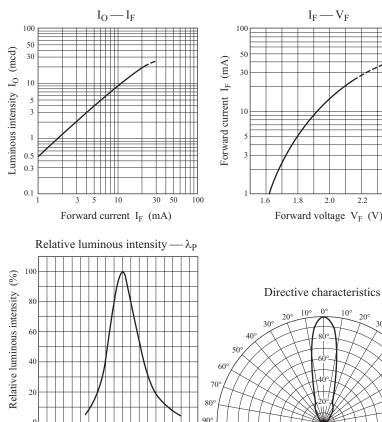
• Orange

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_{\rm F} = 10 \ {\rm mA}$	4.5	9.0		mcd
Reverse current	I _R	$V_R = 3 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 10 {\rm mA}$		1.93	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10 \ {\rm mA}$		630		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \ {\rm mA}$		40		nm

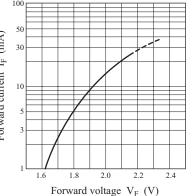
Note) *: Measurement tolerance: ±20%



100

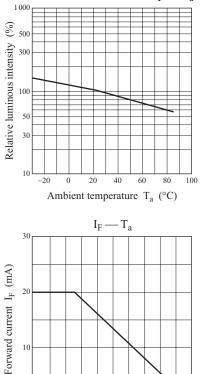
80

700



 $-V_F$





40 Ambient temperature T_a (°C)

60

80

80°

909

60 80 100 0 <mark>L</mark> 0

20

Publication date: January 2009

550

600

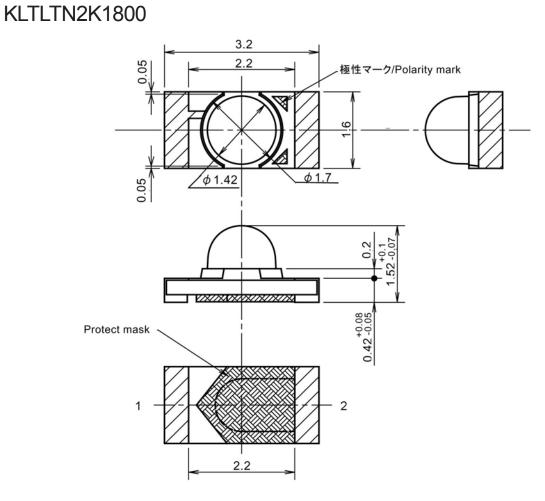
Peak emission wavelength λ_P (nm)

650

Relative luminous intensity (%)

100

Package (Unit: mm)



• Pin name

1: Anode

2: Cathode

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